

**Amendments to the Claims:**

Please delete Claims 1, 4, 6-8, 10, 11, and add New Claims 24-30 as follows:

**Claims:**

1. Canceled
2. Canceled
3. Canceled
4. Canceled
5. Canceled
6. Canceled
7. Canceled
8. Canceled
9. Canceled
10. Canceled
11. Canceled
12. Canceled
13. Canceled
14. Canceled
15. Canceled
16. (withdrawn) A method of fabricating a light emitting device, comprising:  
admixing a luminous substance to a transferable grade molding compound to derive a  
homogeneous mixture;  
pressing and sintering the homogeneous mixture into solid pellets;  
processing the solid pellets for application on a semiconductor surface; and  
depositing the processed solid pellets on the semiconductor surface.
17. (withdrawn) The method of fabricating a light emitting device of Claim 16  
wherein the molding compound is in a pelletized form prior to pressing and sintering the  
homogeneous mixture into solid pellets.

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18. (withdrawn) The method of fabricating a light emitting device of Claim 16 wherein the pelletized molding compound further comprises a clear epoxy.

19. (withdrawn) The method of fabricating a light emitting device of Claim 16 wherein the molding compound is in a powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

20. (withdrawn) The method of fabricating a light emitting device of Claim 19 wherein the powdered molding compound further comprises a clear epoxy.

21. (withdrawn) The method of fabricating a light emitting device of Claim 16 wherein the luminous substance is in powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

22. (withdrawn) The method of fabricating a light emitting device of Claim 16 wherein the light emitted by the light emitting device comprises a white light.

23. (withdrawn) A method of fabricating a light emitting chip comprising depositing an admixed substance of epoxy and a luminous substance around an LED chip located on a copper lead frame.

24. (New) A method of fabricating a light emitting device, comprising:  
admixing a luminous substance to a transferable grade molding compound to derive a homogeneous mixture;

pressing and sintering the homogeneous mixture into solid pellets;  
processing the solid pellets such that the solid pellets are adapted to be applied on a semiconductor surface; and

depositing the processed solid pellets on the semiconductor surface.

25. (New) The method of fabricating a light emitting device of Claim 24 wherein the molding compound is in a pelletized form prior to pressing and sintering the homogeneous mixture into solid pellets.

26. (New) The method of fabricating a light emitting device of Claim 24 wherein the pelletized molding compound further comprises a clear epoxy.

27. (New) The method of fabricating a light emitting device of Claim 24 wherein the molding compound is in a powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

28. (New) The method of fabricating a light emitting device of Claim 27 wherein the powdered molding compound further comprises a clear epoxy.

29. (New) The method of fabricating a light emitting device of Claim 24 wherein the luminous substance is in powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

30. (New) The method of fabricating a light emitting device of Claim 24 wherein the light emitting device is adapted to emit a white light.

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